

P- Channel 40-V (D-S) MOSFET

GENERAL DESCRIPTION

The ME45P04-G is the P-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits , and low in-line power loss are needed in a very small outline surface mount package.

FEATURES

- $R_{DS(ON)} \leq 18m\Omega @ V_{GS} = -10V$
- $R_{DS(ON)} \leq 25m\Omega @ V_{GS} = -4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

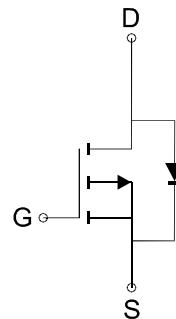
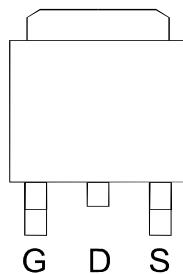
APPLICATIONS

- Power Management in Note book
- DC/DC Converter
- Load Switch
- LCD Display inverter

PIN CONFIGURATION

(TO-252)

Top View



P-Channel MOSFET

Absolute Maximum Ratings ($T_A=25^\circ C$ Unless Otherwise Noted)

Parameter		Symbol	Rating		Unit
Drain-Source Voltage		V_{DSS}	-40		V
Gate-Source Voltage		V_{GSS}	± 20		V
Continuous Drain Current($T_j=150^\circ C$)*	$T_c=25^\circ C$	I_D	-30		A
	$T_c=70^\circ C$		-23		
Pulsed Drain Current		I_{DM}	-100		A
Maximum Power Dissipation*	$T_c=25^\circ C$	P_D	25		W
	$T_c=70^\circ C$		16		
Operating Junction Temperature		T_J	-55 to 150		°C
Thermal Resistance-Junction to Ambient*		$R_{\theta JA}$	Typ	40	°C/W
			Max	50	
Thermal Resistance-Junction to Case*		$R_{\theta JC}$	5		°C/W

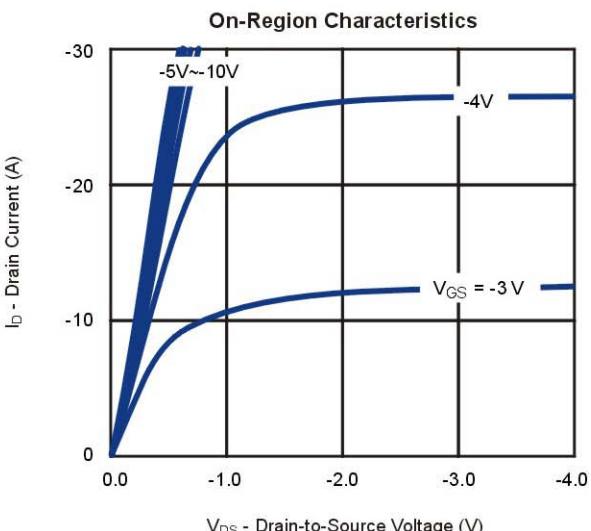
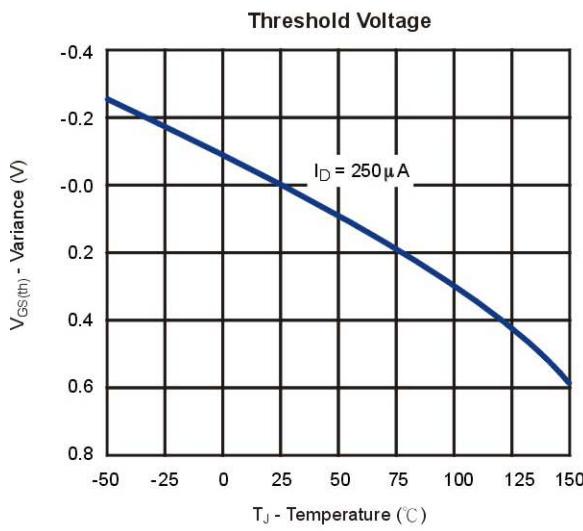
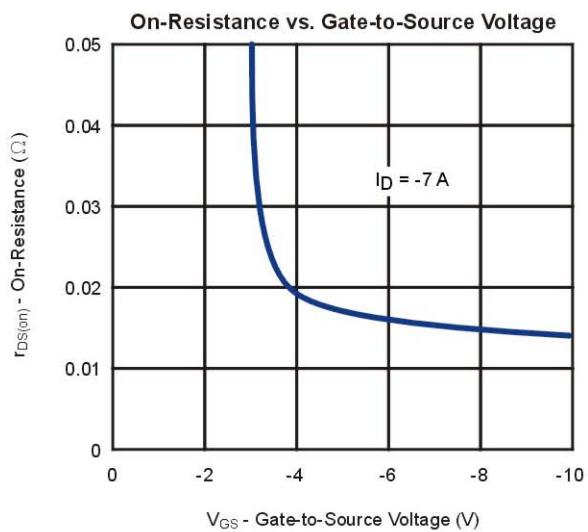
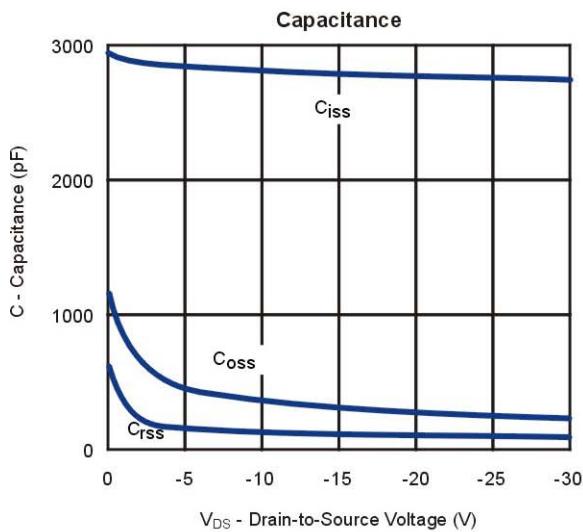
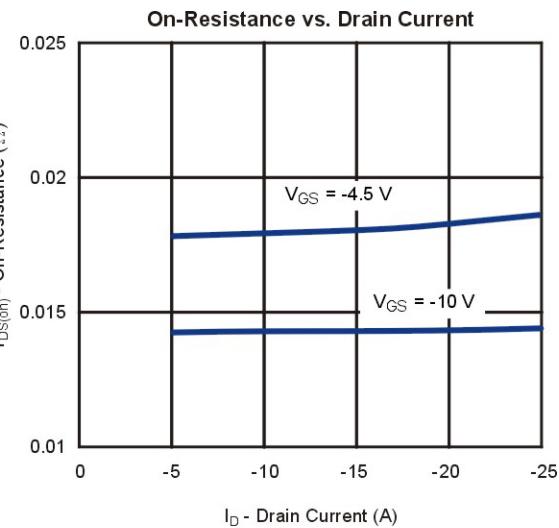
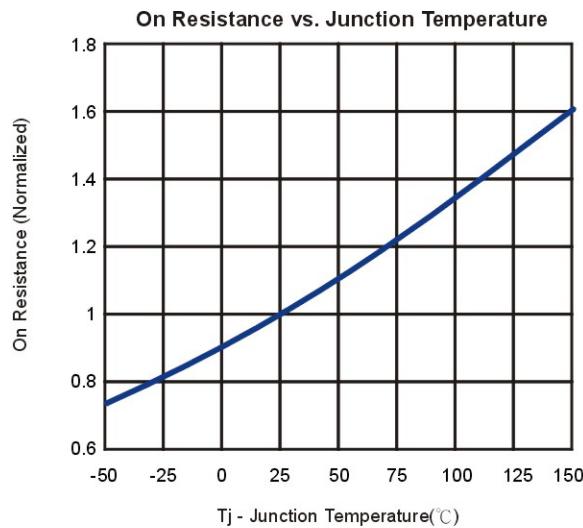
*The device mounted on 1in² FR4 board with 2 oz copper

Electrical Characteristics ($T_A = 25^\circ C$ Unless Otherwise Specified)

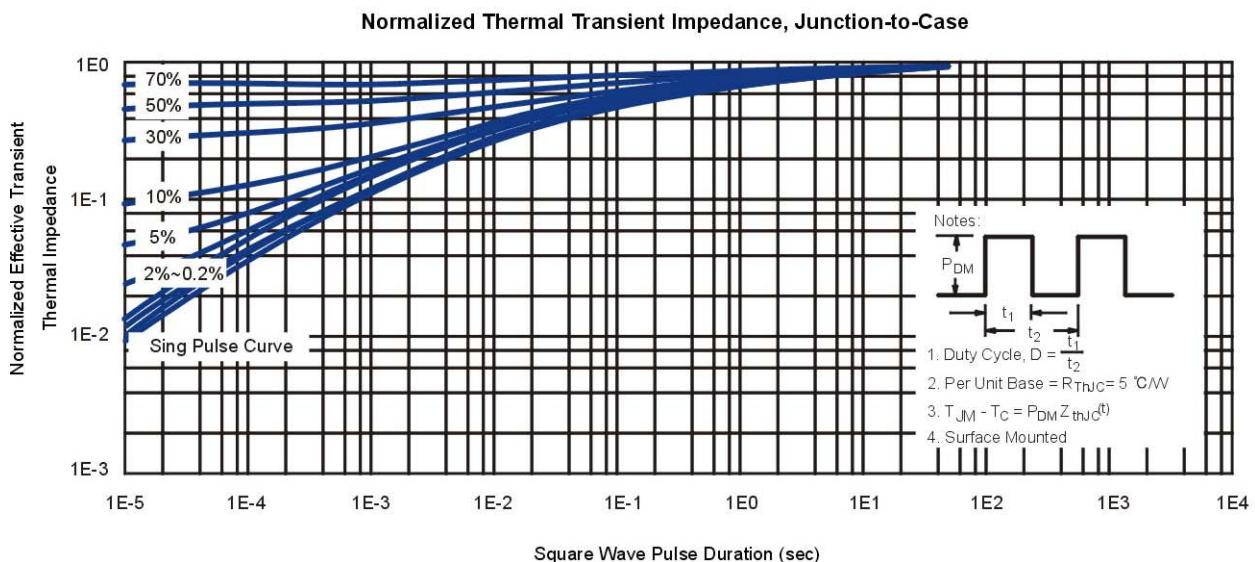
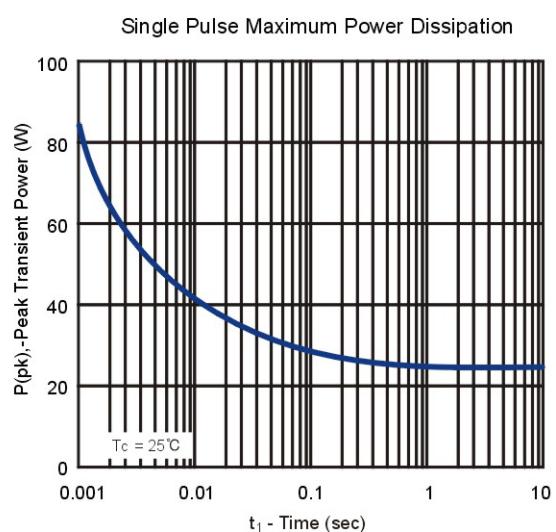
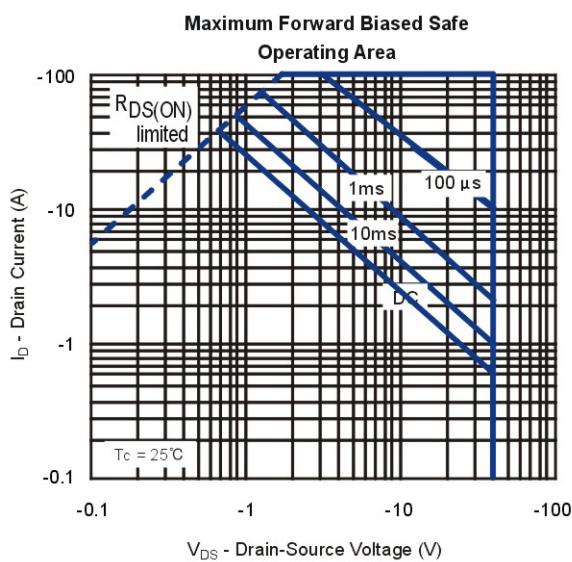
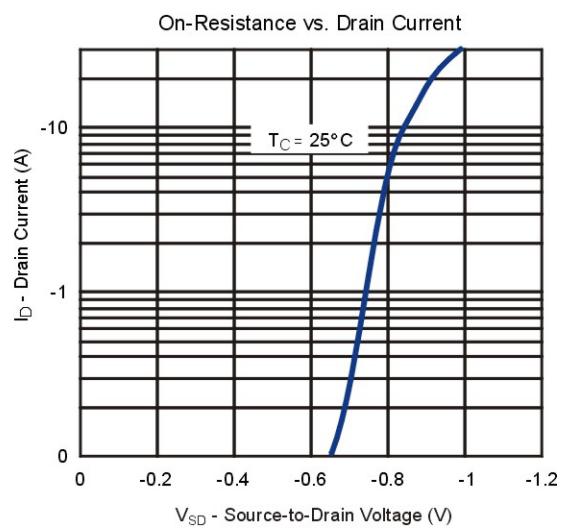
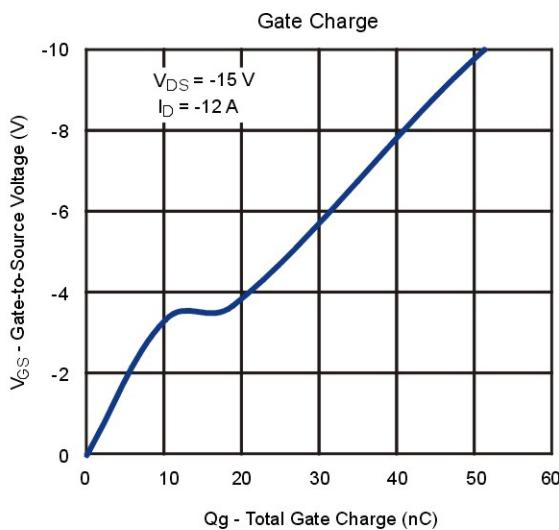
Symbol	Parameter	Limit	Min	Typ	Max	Unit
STATIC						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250 \mu A$	-40			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250 \mu A$	-1.5	-1.8	-3	V
I_{GSS}	Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-40V, V_{GS}=0V$			1	μA
		$V_{DS}=-40V, V_{GS}=0V, T_J=55^\circ C$			10	
$R_{DS(ON)}$	Drain-Source On-State Resistance ^a	$V_{GS}=-10V, I_D= -12A$		15	18	$m\Omega$
		$V_{GS}=-4.5V, I_D= -6A$		18	25	
V_{SD}	Diode Forward Voltage	$I_S=-1.7A, V_{GS}=0V$		0.78	1.2	V
DYNAMIC						
Q_g	Total Gate Charge	$V_{DS}=-20V, V_{GS}=-4.5V, I_D=-12A$		25	33	nC
Q_{gs}	Gate-Source Charge			11		
Q_{gd}	Gate-Drain Charge			9.5		
R_g	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, f=1MHz$		8.5		Ω
C_{iss}	Input capacitance	$V_{DS}=-20V, V_{GS}=0V, F=1MHz$		2760	3726	pF
C_{oss}	Output Capacitance			260		
C_{rss}	Reverse Transfer Capacitance			85		
$t_{d(on)}$	Turn-On Delay Time	$V_{DD}=-15V, R_L=15\Omega$ $I_D=-1A, V_{GEN}=-10V, R_G=6\Omega$		48	64	ns
t_r	Turn-On Rise Time			24	32	
$t_{d(off)}$	Turn-Off Delay Time			88	118	
t_f	Turn-On Fall Time			34	45	

Notes:a. Pulse test; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$

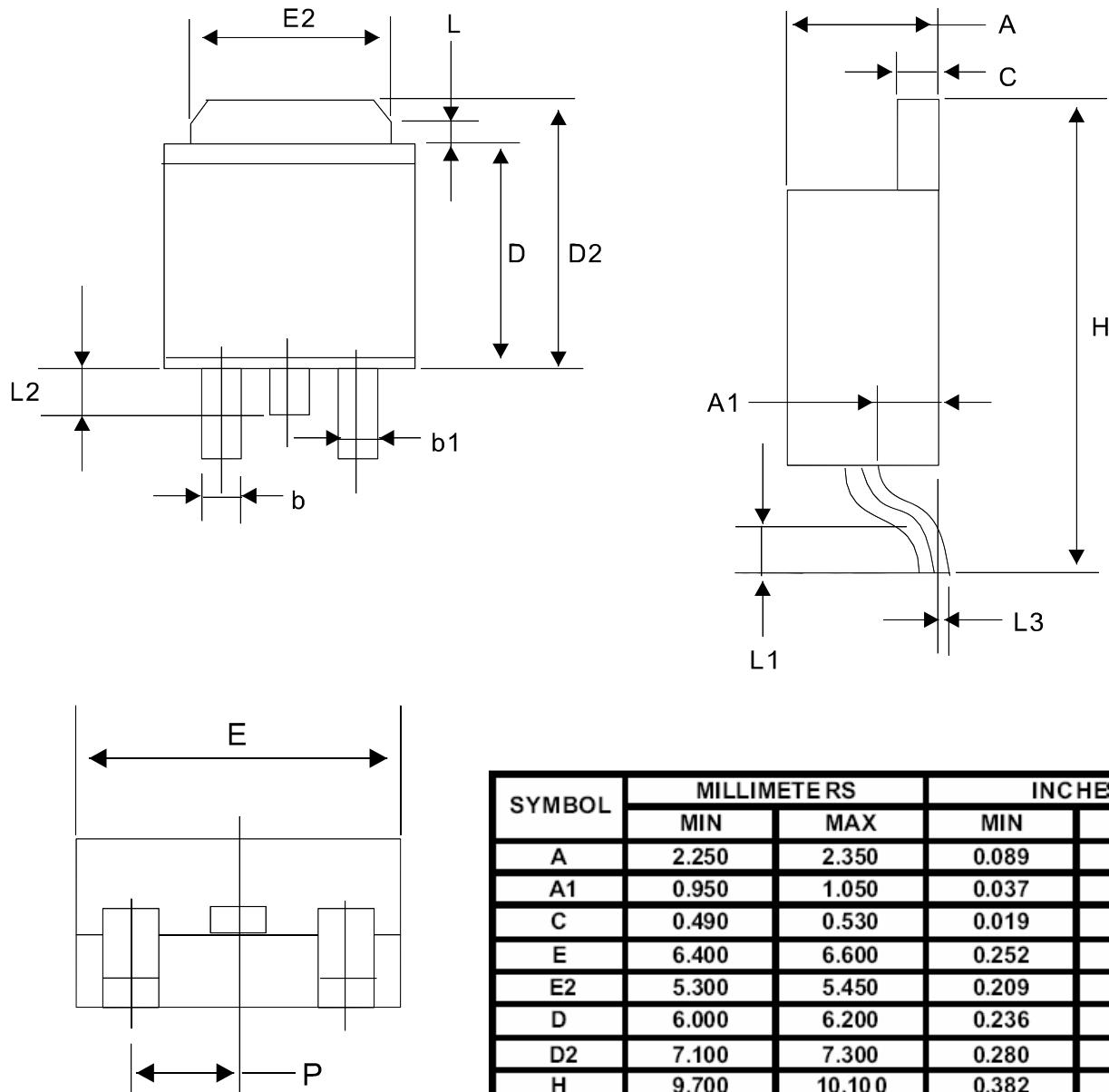
Typical Characteristics ($T_J = 25^\circ\text{C}$ Noted)



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TO-252 Package Outline



SYMBOL	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.250	2.350	0.089	0.093
A1	0.950	1.050	0.037	0.041
C	0.490	0.530	0.019	0.021
E	6.400	6.600	0.252	0.260
E2	5.300	5.450	0.209	0.215
D	6.000	6.200	0.236	0.244
D2	7.100	7.300	0.280	0.287
H	9.700	10.100	0.382	0.398
L	0.600	Ref	0.024	Ref
L1	1.425	1.625	0.056	0.064
L2	0.650	0.850	0.026	0.033
L3	0.020	0.120	0.001	0.005
b	0.770	0.850	0.030	0.033
b1	0.840	0.940	0.033	0.037
P	2.290	BSC	0.090	BSC

